/ Revised record

/ Descriptions

Schottky Diode in a TO-263 Plastic Package.

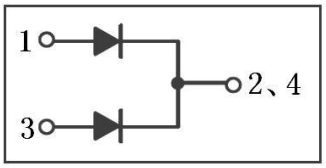
/ Features

Low power loss, high efficiency. HF product.

/ Applications

For use in low voltage,high frequency inverters, free wheeling, and polarity protection applications.

/ Equivalent Circuit



/ Pinning

PIN1 Anode PIN 2 4 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

See Marking Instructions.

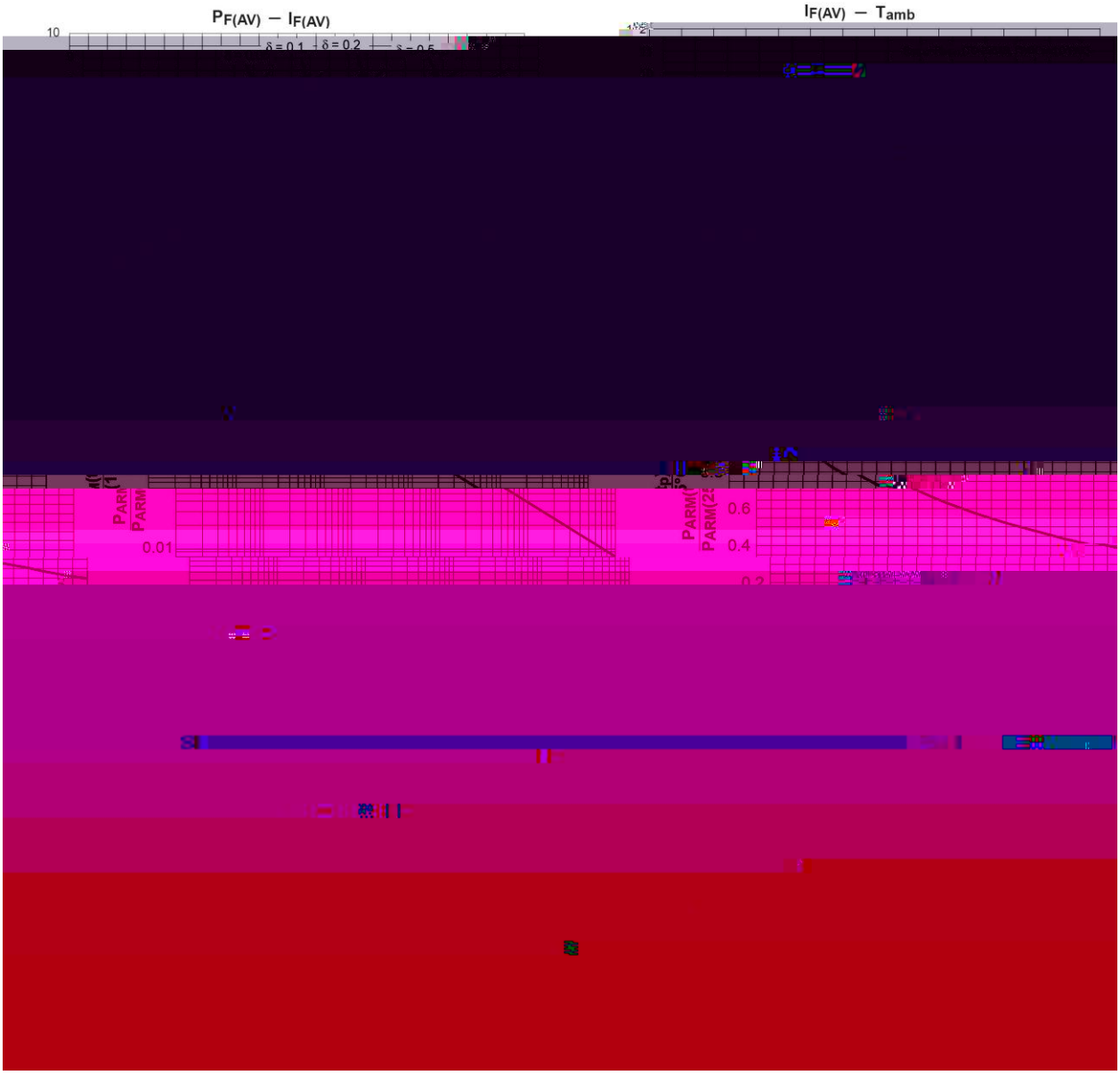
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	150	V
RMS Forward Current	$I_{F(RMS)}$	30	A
Average Rectified Forward Current	$I_{F(AV)}$	10	A
	$I_{F(AV)}$ total	20	A
Non-Repetitive Peak Forward Surge Current	I_{FSM}	180	A
Thermal Resistance Junction to Case	R	2.2	/W
Junction Temperature Range	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

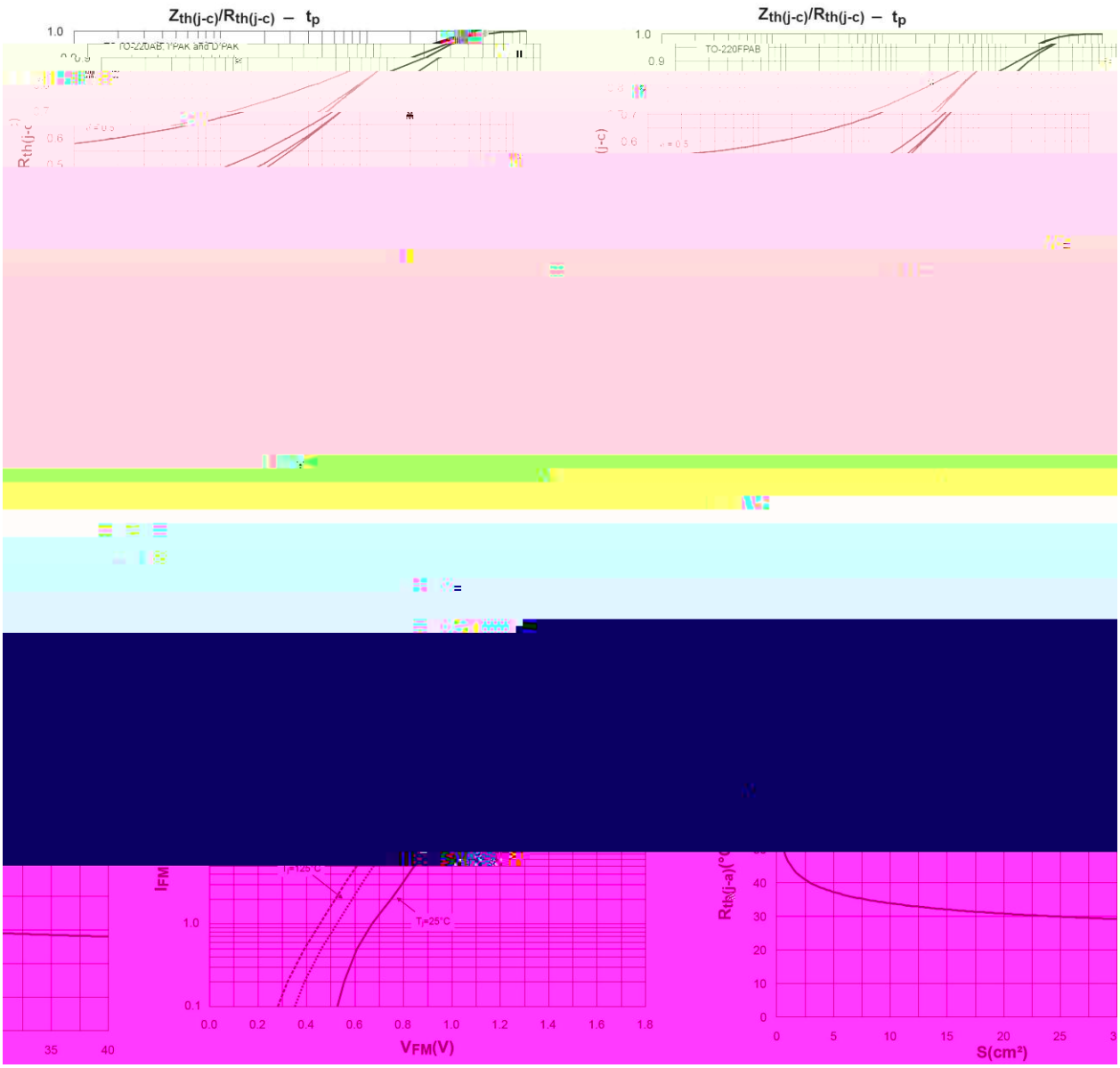
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Forward Voltage	V_F	I_F =10A(T_C=25)			0.92	V
		I_F =10A(T_C=125)		0.69	0.75	V
		I_F =20A(T_C=25)			1.0	V
		I_F =20A(T_C=125)		0.79	0.86	V
Instantaneous Reverse Current	I_R	V_R=150V(T_C=25)			5.0	uA
		V_R=150V(T_C=125)			5.0	mA
Voltage Rate of Change	dv/dt				10000	

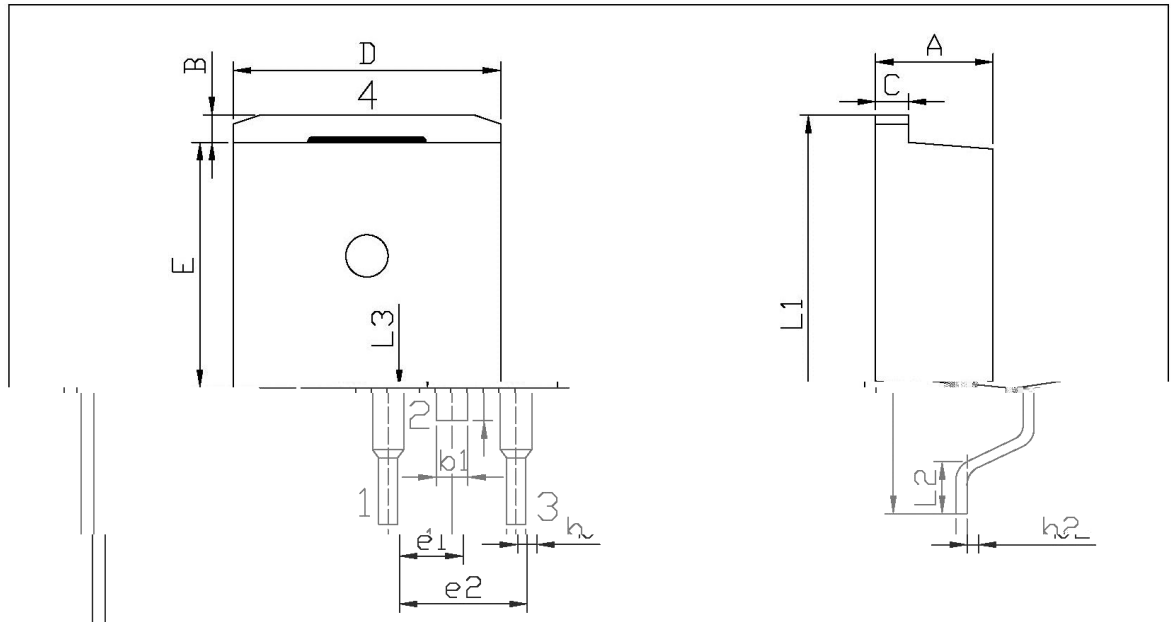
/ Electrical Characteristic Curve



/ Electrical Characteristic Curve



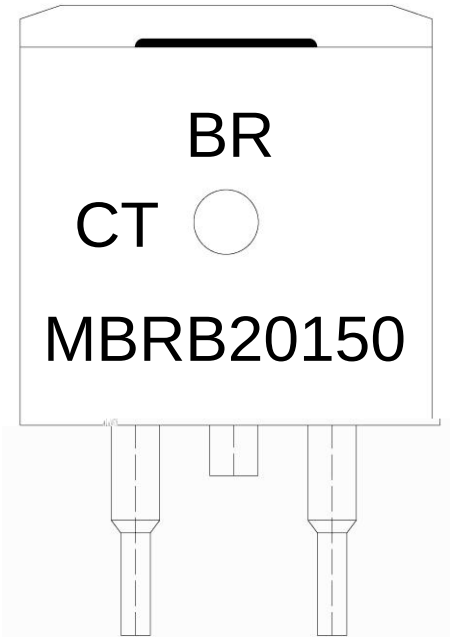
/ Package Dimensions



单位：mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	4.30	4.70	E	9.00	9.40
b	0.70	0.90	e2	4.88	
b2	0.40	0.60	L2		
C	1.20	1.40			
D	9.80	10.20			

/ Marking Instructions



Note:

BR:	Company Code
MBRB20150	Product Type.
CT:	Internal Structure
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)

					Note:
1		25 150		60 90sec;	1.Preheating:25~150 , Time:60~90sec.
2		245 5		5 0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3			2 10 /sec.		3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5	10 1 sec.	Temp.:260±5	Time:10±1 sec	

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)

/ TUBE

Package Type	Units					Dimension		(unit mm³)

/ Notices